Intertek UKAS RoHS COMPLIANT REACH

YEK GLASS
New Age Glass Developer

Packaging Glass Wafers

Ver 0.1

Product Information

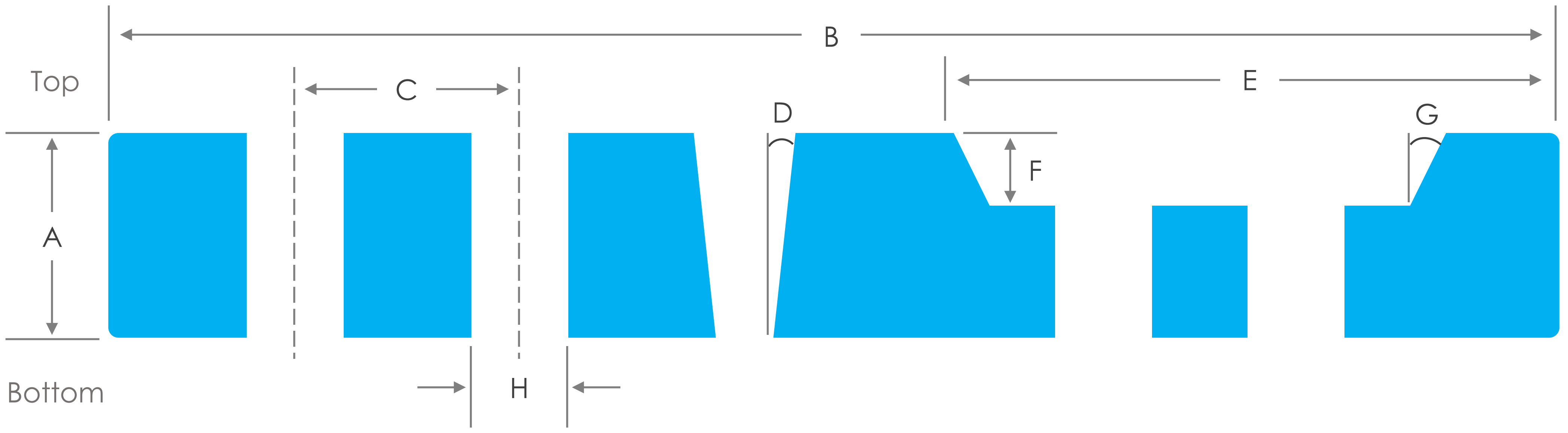
We are able to develop and process glass wafers in-house by combining our mold fabrication techniques with our innovative glass molding processes. Utilizing this technology, we can create structures which are considered difficult with conventional glass structuring techniques, such as complex shapes and precise sidewall angles.

Application

- Wafer-Level-Packaging (WLP)
- Pressure Sensors, Gyroscopes
- LED Encapsulation
- MEMS & Sensors

Specifications

- Wafer diameter from 2” to 12"
- With through holes and cavities
- High accuracy and low tolerance
- Thickness from 350 μm
- Customer specific designs, patterns
- Optional coatings available



The panel sizes listed are for our standard production models, but can customized to support unique specifications.

-	A	B	C	D	E	F	G	H
Spec	350μm ↑ (±20μm)	~12 inch	500μm ↑ (±50μm)	2° ↑	Φ250μm ↑	350μm ↑	20° ↑	Φ200μm ↑
Material	Borofloat 33, Sodalime							

MEMS & Sensors Industry Group® semi

We are proudly a member of IGCA

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